



Brooks

COPIE IAP56

MAY 22 2006

PATENT & TRADEMARK OFFICE

My residence, post office address and citizenship are as stated below next to my name.

METHOD FOR MANUFACTURING SEMICONDUCTOR DEVICE AND SUBSTRATE PROCESSING
APPARATUS

☐ was filed on _____ as United States Application Number or PCT International

Application Number _____ and was amended on _____ (if applicable).

I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56.

Priority Claimed

2002-276076	Japan	20/9/2002
(Number)	(Country)	(Day/Month/Year Filed)
2002-276076	Japan	20/9/2002
(Number)	(Country)	(Day/Month/Year Filed)
2002-276076	Japan	20/9/2002
(Number)	(Country)	(Day/Month/Year Filed)
2002-276076	Japan	20/9/2002
(Number)	(Country)	(Day/Month/Year Filed)

☒ Yes ☐ No☐ Yes ☐ No☐ Yes ☐ No☐ Yes ☐ No

(See note B) ☐ See attached list for additional prior foreign applications

Status

(Application Serial No.)	(Filing Date)
(Application Serial No.)	(Filing Date)
(Application Serial No.)	(Filing Date)

☐ Patented ☐ Pending ☐ Abandoned☐ Patented ☐ Pending ☐ Abandoned☐ Patented ☐ Pending ☐ Abandoned

I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith:

23850

PATENT TRADEMARK OFFICE

Please direct all communications to the following address:

23850

PATENT TRADEMARK OFFICE

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Title 18 of the United States Code, ' 1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

(See note C)

Full name of sole or first inventor (given name, family name)

Sadayoshi HORII

Inventor's signature

Sadayoshi Horii

Date

March 28, 2005

Residence

Same as the Post Office Address

Citizenship

Japanese

Post Office Address

c/o HITACHI KOKUSAI ELECTRIC INC.

14-20, Higashi-Nakano 3-chome, Nakano-ku, Tokyo 164-8511 Japan

Full name of second inventor (given name, family name)

Hironobu MIYA

Inventor's signature

Hironobu Miya

Date

March 28, 2005

Residence

Same as the Post Office Address

Citizenship

Japanese

Post Office Address

c/o HITACHI KOKUSAI ELECTRIC INC.

14-20, Higashi-Nakano 3-chome, Nakano-ku, Tokyo 164-8511 Japan

Full name of third inventor (given name, family name)

Yoshiaki HASHIBA

Inventor's signature

Yoshiaki Hashiba

Date

March 28, 2005

Residence

Same as the Post Office Address

Citizenship

Japanese

Post Office Address

c/o HITACHI KOKUSAI ELECTRIC INC.

14-20, Higashi-Nakano 3-chome, Nakano-ku, Tokyo 164-8511 Japan

Full name of fourth inventor (given name, family name)

Inventor's signature

Date

Residence

Citizenship

Post Office Address

Full name of fifth inventor (given name, family name)

Inventor's signature

Date

Residence

Citizenship

Post Office Address

DECLARATION FOR U.S. PATENT APPLICATION

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

METHOD FOR MANUFACTURING SEMICONDUCTOR DEVICE AND SUBSTRATE PROCESSING APPARATUS

the specification of which is attached hereto unless the following is checked

☐ was filed on _____ as United States Application Number or PCT International

Application Number _____ and was amended on _____ (if applicable).

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claim(s), as amended by any amendment referred above.

I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, § 119 (a) – (d) of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application for which priority is claimed.

(List prior foreign applications. See note A)

Priority Claimed

2002-276076 Japan 20/9/2002
(Number) (Country) (Day/Month/Year Filed)

☒ Yes ☐ No

(Number) (Country) (Day/Month/Year Filed)

☐ Yes ☐ No

(Number) (Country) (Day/Month/Year Filed)

☐ Yes ☐ No

(Number) (Country) (Day/Month/Year Filed)

☐ Yes ☐ No

(See note B)

☐ See attached list for additional prior foreign applications

I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56 which became available between the filing date of the prior application and the national or PCT international filing date of this application.

(List prior U.S. Applications)

Status

(Application Serial No.) (Filing Date)

☐ Patented ☐ Pending ☐ Abandoned

(Application Serial No.) (Filing Date)

☐ Patented ☐ Pending ☐ Abandoned

(Application Serial No.) (Filing Date)

☐ Patented ☐ Pending ☐ Abandoned

I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith:

23850

PATENT TRADEMARK OFFICE

Please direct all communications to the following address:

23850

PATENT TRADEMARK OFFICE

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Title 18 of the United States Code, ' 1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

(See note C) Full name of sole or first inventor (given name, family name) Susumu HORITA
Inventor's signature Susumu Horita Date April 5, 2005
Residence Same as the Post Office Address Citizenship Japanese
Post Office Address 1-50, Asahidai, Nomi-shi, Ishikawa 923-1211 Japan

Full name of second inventor (given name, family name) Yasunori NAKATA
Inventor's signature Y. Nakata Date April 5, 2005
Residence Same as the Post Office Address Citizenship Japanese
Post Office Address 268-4, Kubo 6-chome, Kanazawa-shi, Ishikawa 921-8151 Japan

Full name of third inventor (given name, family name) Masao SEKI
Inventor's signature Masao Seki Date April 5, 2005
Residence Same as the Post Office Address Citizenship Japanese
Post Office Address 35, Nakamachi, Mattou-shi, Ishikawa 924-0877 Japan

Full name of fourth inventor (given name, family name) _____
Inventor's signature _____ Date _____
Residence _____ Citizenship _____
Post Office Address _____

Full name of fifth inventor (given name, family name) _____
Inventor's signature _____ Date _____
Residence _____ Citizenship _____
Post Office Address _____